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 Inputs Are TTL-Voltage Compatible Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption 	CD54ACT138 F PACKAGE CD74ACT138 E OR M PACKAGE (TOP VIEW)
 Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems 	A [1 16] V _{CC} B [2 15] Y0 C [3 14] Y1
 Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception 	G2A [] 4 13]] Y2 G2B [] 5 12]] Y3
 Balanced Propagation Delays ±24-mA Output Drive Current Fanout to 15 F Devices 	G1 [6 11] Y4 Y7 [7 10] Y5 GND [8 9] Y6
SCR-Latchun-Resistant CMOS Process and	

- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

description/ordering information

The 'ACT138 decoders/demultiplexers are designed for high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications (see Application Information).

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – E	Tube	CD74ACT138E	CD74ACT138E
–55°C to 125°C	SOIC – M	Tube	CD74ACT138M	ACT138M
-55°C to 125°C	50IC - M	Tape and reel	CD74ACT138M96	ACTISON
	CDIP – F	Tube	CD54ACT138F3A	CD54ACT138F3A

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

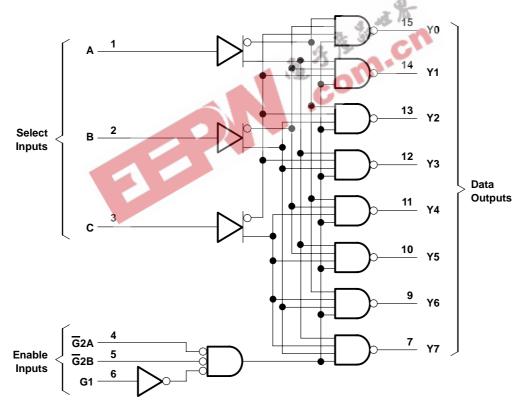


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	FUNCTION TABLE												
ENA	BLE INF	PUTS	SEL	ECT INF	UTS	OUTPUTS							
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	н	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
Х	Х	н	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
L	Х	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
н	L	L	L	L	Н	н	L	Н	Н	Н	Н	Н	Н
н	L	L	L	Н	L	н	Н	L	Н	Н	Н	Н	Н
н	L	L	L	Н	Н	н	Н	н	L	Н	Н	Н	Н
н	L	L	н	L	L	н	Н	н	Н	L	Н	Н	Н
н	L	L	н	L	Н	н	Н	Н	Н	Н	L	Н	Н
н	L	L	н	Н	L	н	Н	Н	Н	Н	Н	L	Н
н	L	L	н	Н	н	н	Н	н	Н	Н	Н	Н	L

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I_{IK} ($V_I < 0$ V or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	67°C/W
M package	73°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		T _A = 2	25°C	–55° 125		–40°(85°		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT
				MIN	MIN MAX		MAX	MIN	MAX	
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4		
Vau	$\lambda = \lambda = \alpha \lambda$	I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		V
∨он	$V_I = V_{IH} \text{ or } V_{IL}$	I _{OH} = -50 mA†	5.5 V			3.85				v
		I _{OH} = -75 mA†	5.5 V					3.85		
	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1	V
Val		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65			
		I _{OL} = 75 mA†	5.5 V						1.65	
lj	$V_{I} = V_{CC}$ or GND		5.5 V		±0.1		±1		±1	μA
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μA
∆I _{CC} ‡	$V_{I} = V_{CC} - 2.1 V$		4.5 V to 5.5 V		2.4	2	3		2.8	mA
Ci					10	, Ju	10		10	pF

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C. ‡ Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A, B, or C	0.83
$\overline{G2A}$ or $\overline{G2B}$	1
G1	0.42

Unit Load is ∆ICC limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

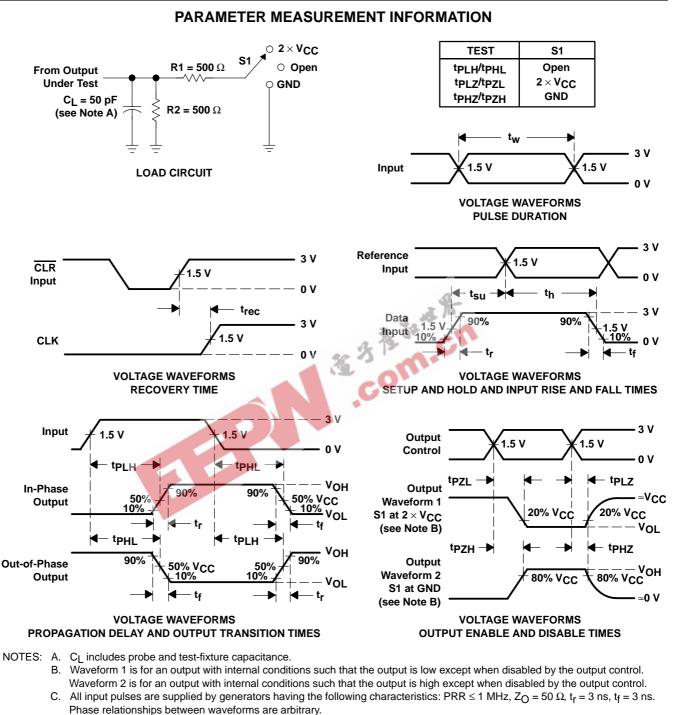
PARAMETER	FROM	TO (OUTPUT)			C to °C	–40° 85°	UNIT
		(661461)	MIN	MAX	MIN	MAX	
^t PLH	A, B, C	Any V	3	12	3.1	10.9	ns
^t PHL	А, В, С	Any Y	3	12	3.1	10.9	115
^t PLH	01	Any Y	2.8	11	2.8	10	ns
^t PHL	G1		2.8	11	2.8	10	115
^t PLH	G2A, G2B		2.6	10.5	2.7	9.5	ns
^t PHL	G2A, G2D	Any Y	2.6	10.5	2.7	9.5	115

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER			
Cpd	Power dissipation capacitance	110	pF	



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- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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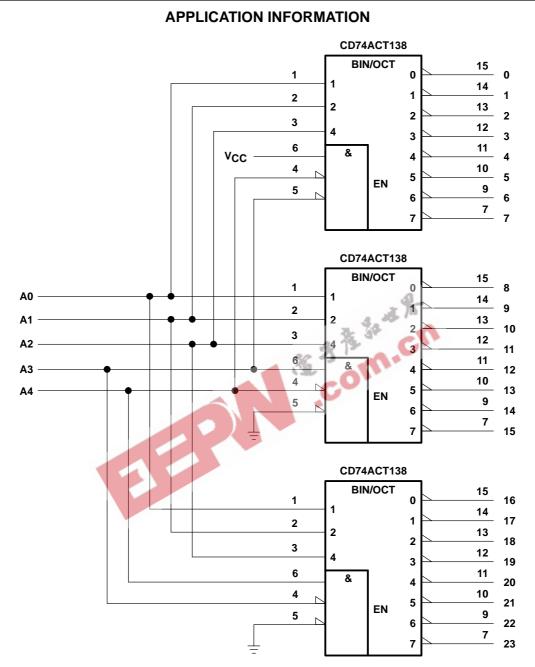
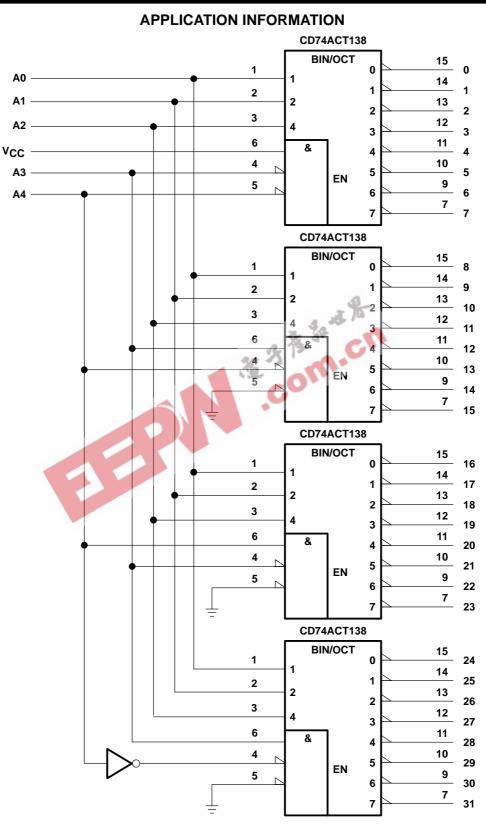


Figure 2. 24-Bit Decoding Scheme



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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

PINS ** 14 16 18 20 DIM 0.300 0.300 0.300 0.300 В А (7,62) (7,62) (7,62) (7,62) BSC BSC BSC BSC 8 14 0.785 1.060 .840 0.960 B MAX (19,94)(21, 34)(24, 38)(26, 92)B MIN С 0.300 0.300 0.310 0.300 C MAX (7, 62)(7,62) (7, 62)(7, 87)C MIN 7 0.245 0.245 0.220 0.245 0.065 (1,65) 0.045 (1,14) (6, 22)(6, 22)(5, 59)(6, 22)0.060 (1,52) - 0.005 (0,13) MIN Α -0.015 (0,38) 0.200 (5,08) MAX Seating Plane 0.130 (3,30) MIN 0.026 (0,66) 0.014 (0,36) 0°-15° 0.100 (2,54) 0.014 (0,36) 0.008 (0,20) 4040083/F 03/03

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



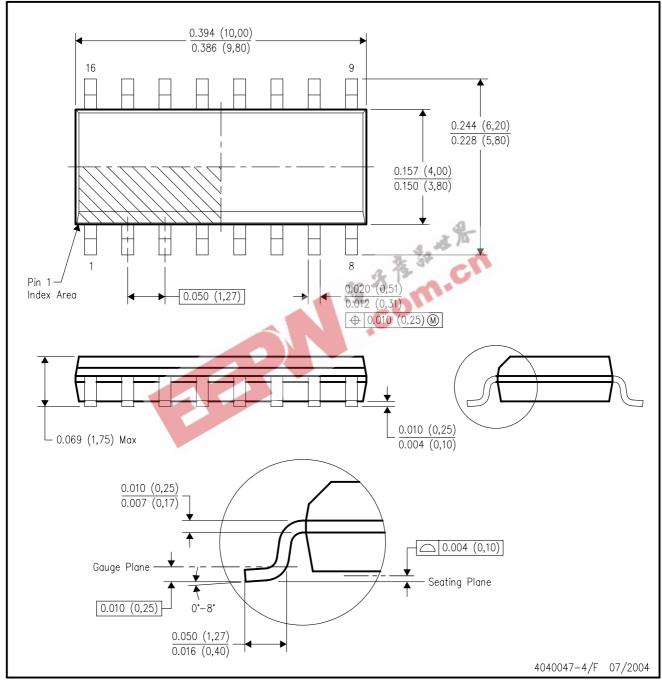
A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.

- \triangle Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



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